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KEY DOCKET NO: AB-1104 US

REC

U.S. DEPARTMENT OF COMMERCE  
PATENT AND TRADEMARK OFFICE

2-14-01



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TO THE HONORABLE DIRECTOR OF THE UNITED STATES PATENT AND TRADEMARK OFFICE. PLEASE RECORD THE ATTACHED ORIGINAL DOCUMENTS OR COPY THEREOF.

## 1. Name of conveying parties:

- (a) Sung Jin Kim  
(b) Sun Jin Son

Additional name(s) of conveying party(ies) attached?

☐ Yes☒ No

## 2. Name and address of receiving party:

Name: Amkor Technology, Inc.

Street Address: 1900 South Price Road

City: Chandler

AZ

85248-1604

Country: US

## 3. Nature of Conveyance:

- ☒ Assignment ☐ Merger  
☐ Security Agreement ☐ Change of Name  
☐ Other \_\_\_\_\_

Execution Date: February 13, 2001; February 12, 2001

## Name and address of receiving party(ies):

Name:

Street Address:

City:

Country:

Additional name(s) &amp; address(es) attached?

☐ Yes☒ No

## 4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: February 13, 2001; February 12, 2001

## A. Patent Application No.(s) -

Title: Printed Circuit Board For Semiconductor Package  
And Method For Manufacturing The Same

## B. Patent No.(s)

Additional numbers attached?



Yes



No

## 5. Name and address of party to whom correspondence concerning document should be mailed:

Name: James E. ParsonsInternal Address: SKJERVEN MORRILL MacPHERSON LLPStreet Address: 25 METRO DRIVE, SUITE 700City SAN JOSE State CA Zip 951106. Total number of applications and patents involved: 1

## 7. Total fee (37 CFR 3.41): \$40.00



Authorized to be charged to Deposit Account 19-2386



Charge Deposit Account 19-2386 for any additional fees required for this conveyance and credit deposit account 19-2386 any amounts overpaid

DO NOT USE THIS SPACE

## 8. Statement and signature.

*To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.*James Parsons  
Name of Person SigningJames E. Parsons  
SignatureFebruary 14, 2001  
Date

Total number of pages comprising cover sheet: 1

**ASSIGNMENT**

For good and valuable consideration, receipt of which is hereby acknowledged, we

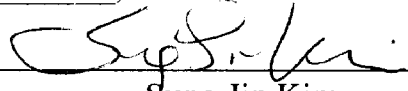
Sung Jin Kim of Seoul, Republic of Korea  
Sun Jin Son of Seoul, Republic of Korea

hereby sell, assign and transfer to Amkor Technology, Inc., a Delaware corporation, having a place of business at 1900 South Price Road, Chandler, AZ 85248-1604, its successors and assigns, the entire right, title and interest throughout the world in our invention in:

Printed Circuit Board For Semiconductor Package  
 And Method For Manufacturing The Same

for which we have executed a United States patent application on or about the date of this assignment, and all patent applications and patents of every country for said invention, including divisions, reissues, continuations and extensions thereof, and all rights of priority resulting from the filing of said applications; we authorize the above-named assignee to apply for patents of foreign countries for said invention, and to claim all rights of priority without further authorization from us; we agree to execute all papers useful in connection with said United States and foreign applications, and generally to do everything possible to aid said assignee, their successors, assigns and nominees, at their request and expense, in obtaining and enforcing patents for said invention in all countries; and we request that the United States Patent and Trademark Office issue all patents granted for said invention to the above-named assignee, its successors and assigns.

Executed this 13 day of Feb, 2001.

  
Sung Jin Kim

WITNESSED:

Y. S. Yoo  
 Signature

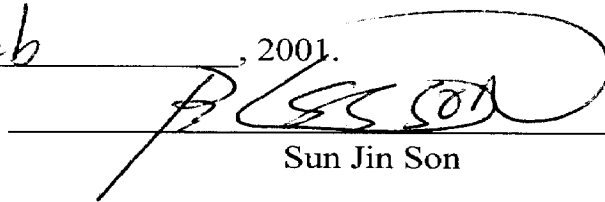
Feb. 13, 2001

Date

Yong Suk Yoo

Type or print name of witness

Executed this 12 day of Feb, 2001.

  
\_\_\_\_\_  
Sun Jin Son

WITNESSED: Y. S. Yoo

Signature Feb. 12, 2001

Date Yong Suk Yoo

Type or print name of witness